



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION: Hui ZHONG, et al.

SERIAL NO.: 10/049,270

GAU: 2841

FILED: June 27, 2002

EXAMINER: Tuan T. DINH

FOR: MULTILAYER PRINTED WIRING BOARD, SOLDER RESIST COMPOSITION, METHOD FOR MANUFACTURING MULTILAYER PRINTED WIRING BOARD, AND SEMICONDUCTOR DEVICE

LETTER SUBMITTING REPLACEMENT DRAWING SHEET(S)

COMMISSIONER FOR PATENTS
Alexandria, VA 22313

SIR:

Responsive to the below indicated communication, the following drawing sheets are submitted herewith:

1 Replacement Drawing Sheets _____ New Drawing Sheets
 _____ Annotated Drawing Sheets

Official Action dated November 5, 2007
 Notice of Allowance/Issue Fee dated _____
 Other dated _____

The changes and/or modifications made include the following:

A detailed view of the solder resist layer 14 as described in the specification has been added.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Customer Number

22850

Tel. (703) 413-3000
Fax. (703) 413-2220
(OSMMN 06/04)

Richard D. Kelly
Registration No. 27,757


Edwin D. Garlepp
Registration No. 45,330